

ABSTRACT OF THE DISCLOSURE

According to one aspect of the invention, a wafer processing apparatus is provided. The wafer processing apparatus may include a wafer support, a dispense head, and a solvent bath. The dispense head may be moveable between a position over the wafer support and a position over the solvent bath. When the dispense head is positioned over the solvent bath, a fluid dispensed from the dispense head may enter a drain and nozzles on the dispense head may be exposed to a controlled atmosphere within a chamber of the solvent bath.